

### REMARKS

Applicants respectfully request consideration of the subject application. This Response is submitted in response to the Office Action mailed October 5, 2006. Claims 16-30 are pending. Claims 27-30 are rejected.

In the Office Action Summary, the Examiner indicates that only claims 27-30 are pending. However, in the Preliminary Amendment mailed with the filing of the application, only claims 1-15 and 31-41 were cancelled. Claims 16-26 were not cancelled in that Preliminary Amendment. Accordingly, claims 16-26 are still pending.

### 35 U.S.C. §§ 102 and 103 Rejections

The Examiner has rejected claims 27 and 30 under 35 U.S.C. § 102(e) as being anticipated by Matayabas, et al. (U.S. Patent Publication No. 2003/0128521, hereinafter "Matayabas"), and claims 27 and 30 under 35 U.S.C. § 102(b) as being anticipated by Nakanishi, et al. (U.S. Patent No. 5,403,783, hereinafter "Nakanishi"). The Examiner has rejected claims 28 under 35 U.S.C. § 103(a) as being unpatentable over Matayabas and claim 29 under 35 U.S.C. § 103(a) as being unpatentable over Nakanishi in further view of Takeuchi (U.S. Patent Publication No. 2003/0122242, hereinafter "Takeuchi").

Matayabas is directed to an electronic package which includes a thermal interface material that includes a polymer matrix and thermally conductive filler. Matayabas discloses that the thermal interface material includes silicon-hydride units and vinyl groups, which react together in a crosslinking reaction during the cure. Matayabas does not disclose that the thermal interface material covalently bonds with the heat generating device or the heat dissipating device.

Nakanishi is directed to an electronic device in which a first substrate and a second substrate are bonded together through a covalent bond formed between the first substrate and the second substrate. Nakanishi does not disclose a thermal interface material between a backside of a heat generating device and a bottom surface of a heat dissipating device.

Similarly, Takeuchi does not disclose a thermal interface material as presently claimed.

In contrast, in embodiments of the presently claimed invention, the thermal interface material is covalently bonded to the bottom surface of the heat dissipating device and/or the backside surface of the heat generating device.

Therefore, the cited art fails to teach or suggest all of the limitations of independent claims 16 and 27. Claims 17-26 and 28-30 depend, directly or indirectly, from one of the foregoing independent claims.


Applicants, accordingly, respectfully request withdrawal of the rejections under 35 U.S.C. § 102 and § 103.

Applicants respectfully submit that the present application is in condition for allowance. If the Examiner believes a telephone conference would expedite or assist in the allowance of the present application, the Examiner is invited to call Jennifer Hayes at (408) 720-8300.

Please charge any shortages and credit any overages to Deposit Account No. 02-2666. Any necessary extension of time for response not already requested is hereby requested. Please charge any corresponding fee to Deposit Account No. 02-2666.

Respectfully submitted,  
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